

1     ABSTRACT OF THE DISCLOSURE

          A method of mounting a semiconductor device  
having bumps on a board having pads so that each of  
the bumps is joined to a corresponding one of the pads  
5     is provided. Adhesive to be hardened by heat is  
provided between the semiconductor device and the  
board. The method includes the steps of pressing the  
bumps of the semiconductor device on the pads of the  
10    board, and heating a portion in which each of the  
bumps and a corresponding one of the pads are in  
contact with each other. A pressure of the bumps to  
the pads reaches a predetermined value before a  
\*     temperature of the adhesive to which heat is supplied  
in the above step reaches a temperature at which the  
15    adhesive is hardened.

20

25

30

35

REF ID: A550860